SPECIFICATION FOR APPROVAL

PAD LAYOUT: (UNIT: mm)

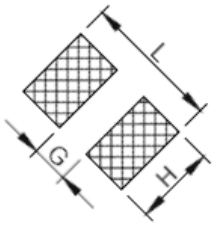


FIG. 1

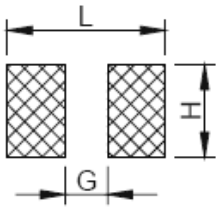
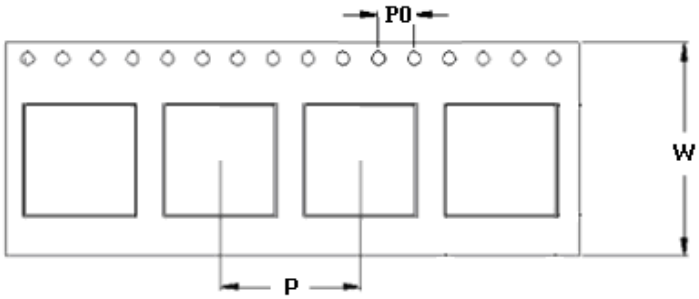


FIG.2

ITEM	FIG.	L (Ref.)	G (Ref.)	H (Ref.)
SCI2D09	1	4.3	1.7	1.3
SCI2D11	2	4.3	2.1	1.3
SCI2D14	2	4.3	2.1	1.3
SCI2D18	2	4.3	2.1	1.3
SCI3D11	2	5.2	2.4	1.5
SCI3D14	2	5.2	2.4	1.5
SCI3D16	2	5.2	2.4	1.5
SCI3D28	2	5.2	2.4	1.5
SCI4D18	2	5.3	1.5	5.3
SCI4D28	2	5.3	1.5	5.3
SCI5D18	2	6.3	2.0	6.3
SCI5D28	2	6.3	2.0	6.3
SCI6D28	2	7.3	2.0	7.3
SCI6D38	2	7.3	2.0	7.3
SCI8D28	2	10.1	6.1	5.0
SCI8D43	2	10.1	6.1	5.0

SPECIFICATION FOR APPROVAL

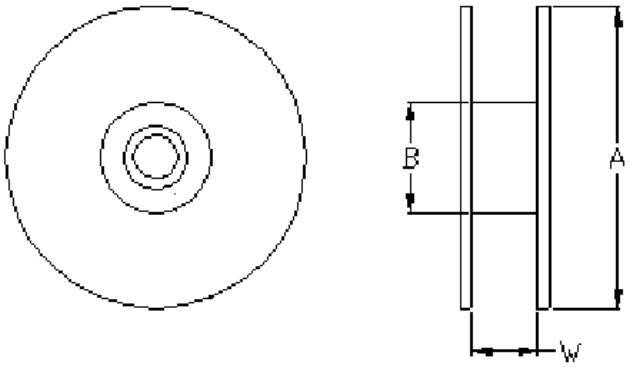
PACKAGING QUANTITY: (UNIT: mm)



TYPE	P	P0	W	BULK	PCS / REEL
SCI2D09	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI2D11	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI2D14	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI2D18	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI3D11	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI3D14	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI3D16	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	3000
SCI3D28	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	2500
SCI4D18	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	2000
SCI4D28	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	2000
SCI5D18	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	2000
SCI5D28	8.0 ± 0.1	4.0 ± 0.1	12 ± 0.3	ν	2000
SCI6D28	12.0 ± 0.1	4.0 ± 0.1	16 ± 0.3	ν	1500
SCI6D38	12.0 ± 0.1	4.0 ± 0.1	16 ± 0.3	ν	1000
SCI8D28	12.0 ± 0.1	4.0 ± 0.1	24 ± 0.3	ν	1000
SCI8D43	12.0 ± 0.1	4.0 ± 0.1	24 ± 0.3	ν	1000

SPECIFICATION FOR APPROVAL

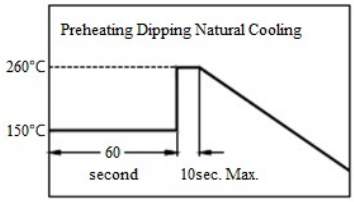
PACKAGING QUANTITY: (UNIT: mm)



TYPE	A	B	W
SCI2D09	330	100	12.5
SCI2D11	330	100	12.5
SCI2D14	330	100	12.5
SCI2D18	330	100	12.5
SCI3D11	330	100	12.5
SCI3D14	330	100	12.5
SCI3D16	330	100	12.5
SCI3D28	330	100	12.5
SCI4D18	330	100	12.5
SCI4D28	330	100	12.5
SCI5D18	330	100	12.5
SCI5D28	330	100	12.5
SCI6D28	330	100	16.5
SCI6D38	330	100	16.5
SCI8D28	330	100	24.5
SCI8D43	330	100	24.5

SPECIFICATION FOR APPROVAL

RELIABILITY AND TEST CONDITIONS:

<table>
<tr><th>ITEM</th><th>PERFORMANCE</th><th>TEST CONDITION</th></tr>
<tr><td>Operating Temperature</td><td>-40~+125℃</td><td></td></tr>
<tr><td>Rated Current</td><td>Refer to standard electrical characteristics list.</td><td></td></tr>
<tr><td>Temperature Rise Test</td><td>40℃ max. (Δt)</td><td></td></tr>
<tr><td>Solder heat Resistance</td><td>Appearance: No significant abnormality.
Inductance change: Within ± 30%.</td><td>Preheat:150℃,60sec.
Solder : H63A
Solder tamperature:260+0-5℃
Flux: rosin
Dip time:10sec. Max.
  </td></tr>
<tr><td>Thermal shock</td><td rowspan="3">Appearance: no damage
Inductance: within±30%of initial value.</td><td>Condition for 1 cycle
Step1:-25±2℃
30±3 min.
Step2:Room temperature 15 min.
Step3:+85±5℃
30±3 min.
Step4:Room temperature 15 min.
Number of cycles:50
<table><tr><th>Phase</th><th>Temperature(℃)</th><th>Time(min)</th></tr><tr><td>1</td><td>-25±2℃</td><td>30±3</td></tr><tr><td>2</td><td>Room Temp.</td><td>15</td></tr><tr><td>3</td><td>+85±2℃</td><td>30±3</td></tr><tr><td>4</td><td>Room Temp.</td><td>15</td></tr></table></td></tr>
<tr><td>Humidity Resistance Test</td><td>Measured:50 times

Temperature:40±2℃.
Applied current: rated current.
Duration:500 hrs.
Humidity:90~95%</td></tr>
<tr><td>High Temperature Resistance Test</td><td>Temperature:85±2℃.
Applied current: rated current.
Duration:500 hrs.</td></tr>
</table>